

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	IPC100N04S5L-1R9	**Issued**	14. May 2021
MA#	MA002835968		
Package	PG-TDSON-8-34	**Weight***	112.43 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.821	0.73	0.73	7300	7300
leadframe	inorganic material	phosphorus	7723-14-0	0.016	0.01		141	
	non noble metal	iron	7439-89-6	0.053	0.05		471	
	non noble metal	copper	7440-50-8	52.842	46.98	47.04	470016	470628
wire	noble metal	gold	7440-57-5	0.044	0.04	0.04	391	391
encapsulation	organic material	carbon black	1333-86-4	0.076	0.07		674	
	plastics	epoxy resin	-	5.990	5.33		53280	
	inorganic material	silicondioxide	60676-86-0	31.846	28.33	33.73	283260	337214
leadfinish	non noble metal	tin	7440-31-5	1.574	1.40	1.40	13999	13999
plating	noble metal	silver	7440-22-4	0.209	0.19	0.19	1861	1861
solder	non noble metal	tin	7440-31-5	0.023	0.02		206	
	noble metal	silver	7440-22-4	0.029	0.03		257	
	non noble metal	lead	7439-92-1	1.105	0.98	1.03	9831	10294
heat sink clip	inorganic material	phosphorus	7723-14-0	0.005			45	
	non noble metal	iron	7439-89-6	0.017	0.02		150	
	non noble metal	copper	7440-50-8	16.828	14.97	14.99	149677	149872
clip plating	noble metal	silver	7440-22-4	0.639	0.57	0.57	5684	5684
heatspreader	inorganic material	phosphorus	7723-14-0	0.000			1	
	non noble metal	iron	7439-89-6	0.000			3	
	non noble metal	copper	7440-50-8	0.310	0.28	0.28	2753	2757
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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